

Wire Arranged	---->	Solder Assembled	---->	Dice Assembled	---->	Solder Assembled
	IPQC		IPQC			↓
The Gluing	<----	Pickling	<----	Conversion	<----	Soldering
↓	IPQC				IPQC	
SKY-GPP	---->	Epoxy Molding	---->	Epoxy Curing	---->	Lead Tin Plating
			IPQC		IPQC	↓
Outgoing Inspection	<----	Stock	<----	Labeling Packing	<----	Appearance Checking



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